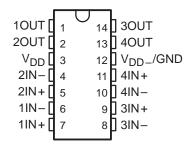
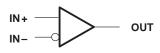
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- Single- or Dual-Supply Operation
- Wide Range of Supply Voltages 1.4 V to 18 V
- Very Low Supply Current Drain 300 μA Typ at 5 V 130 μA Typ at 1.4 V
- Built-In ESD Protection
- High Input Impedance . . . $10^{12} \Omega$ Typ
- Extremely Low Input Blas Current
 5 pA Typ
- Ultrastable Low Input Offset Voltage
- Input Offset Voltage Change at Worst-Case Input Conditions Typically 0.23 μV/Month, Including the First 30 Days
- Common-Mode Input Voltage Range Includes Ground
- Outputs Compatible With TTL, MOS, and CMOS
- Pin-Compatible With LM339

D, N, OR PW PACKAGE (TOP VIEW)



symbol (each comparator)



description

This device is fabricated using LinCMOSTM technology and consists of four independent differential voltage comparators; each is designed to operate from a single power supply. Operation from dual supplies is also possible if the difference between the two supplies is 1.4 V to 18 V. Each device features extremely high input impedance (typically greater than $10^{12} \Omega$), which allows direct interface to high-impedance sources. The outputs are n-channel open-drain configurations and can be connected to achieve positive-logic wired-AND relationships. The capability of the TLC354 to operate from a 1.4-V supply makes this device ideal for low-voltage battery applications.

The TLC354 has internal electrostatic discharge (ESD) protection circuits and has been classified with a 2000-V ESD rating tested under MIL-STD-833C, Method 3015. However, care should be exercised in handling this device as exposure to ESD may result in degradation of the device parametric performance.

The TLC354C is characterized for operation from 0° C to 70° C. The TLC354I is characterized for operation over the industrial temperature range of -40° to 85° C. The TLC354M is characterized for operation over the full military temperature range -55° C to 125° C.

AVAILABLE OPTIONS

	Via may	PAC	CHIP		
TA	V _{IO} max AT 25°C	SMALL OUTLINE (D)	PLASTIC DIP (P)	TSSOP (PW)	FORM (Y)
0°C to 70°C	5 mV	TLC354CD	TLC354CN	TLC354CPW	TLC354Y
-40°C to 85°C	5 mV	TLC354ID	TLC354IN	_	_
-55°C to 125°C	5 mV	TLC354MD	TLC354MN	_	_

The D packages are available taped and reeled. Add R suffix to device type (e.g., TLC354CDR).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

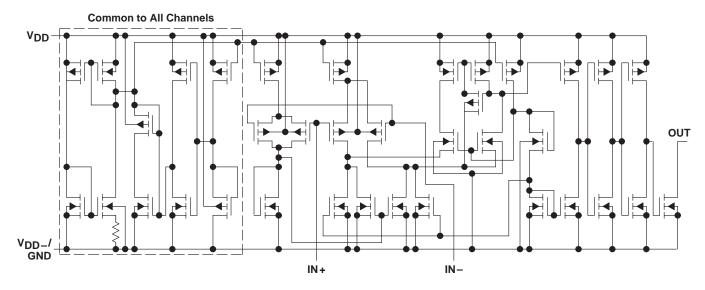
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TEXAS INSTRUMENTS

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equivalent schematic (each comparator)



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V _{DD} (see Note 1)	
Differential input voltage, V _{ID} (see Note 2)	
Input voltage, V _I	V _{DD}
Input voltage range, V _I	0.3 V to 18 V
Output voltage, VO	
Input current, I ₁	
Output current, I _O	
Duration of output short circuit to ground (see Note 3)	Unlimited
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A : TLC354C	0°C to 70°C
TLC354I	–40°C to 85°C
TLC354M	
Storage temperature range	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values except differential voltages are with respect to network ground.
 - 2. Differential voltages are at IN+ with respect to IN-.
 - 3. Short circuits from outputs to VDD can cause excessive heating and eventual device destruction.

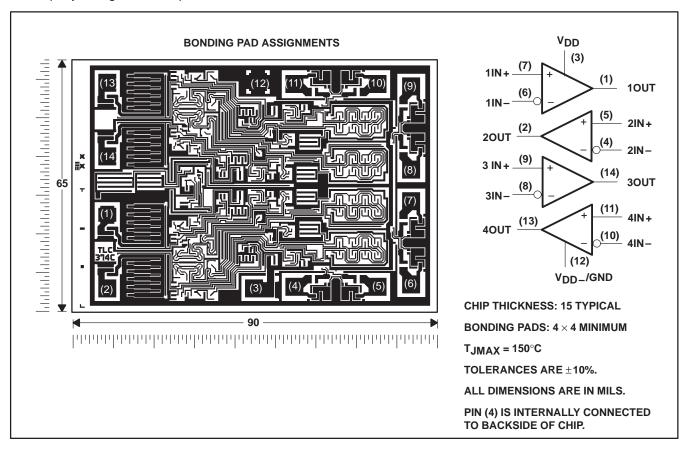
DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR	DERATE ABOVE T _A	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
D	500 mW	7.6 mW/°C	84°C	500 mW	494 mW	190 mW
N	500 mW	9.2 mW/°C	96°C	500 mW	500 mW	230 mW
PW	700 mW	5.6 mW/°C	25°C	448 mW	N/A	N/A



TLC364Y chip information

This chip, when properly assembled, displays characteristics similar to the TLC354C. Thermal compression or ultrasonic bonding can be used on the doped-aluminum bonding pads. Chips can be mounted with conductive epoxy or a gold-silicon preform.



recommended operating conditions

		TLC3	54C	TLC	354I	TLC3	54M	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
Supply voltage, V _{DD}		1.4	16	1.4	16	1.4	16	V
	V _{DD} = 1.4 V	0	0.2	0	0.2	0	0.2	
Common-mode input voltage, V _{IC}	$V_{DD} = 5 V$	0	3.5	0	3.5	0	3.5	V
	$V_{DD} = 10 \text{ V}$	0	8.5	0	8.5	0	8.5	
Operating free-air temperature, TA		0	70	-40	85	-55	125	°C

electrical characteristics at specified free-air temperature, $V_{DD} = 1.4 \text{ V}$

	PARAMETER	TEST COL	NDITIONS	T. †	TI	_C354C		T	LC354I		TI	_C354M		UNIT
	PARAMETER	TEST CO	NDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
\/10	Input offset voltage	Vio - Vionmin	See Note 4	25°C		2	5		2	5		2	5	mV
VIO	input onset voltage	$V_{IC} = V_{ICRmin}$	See Note 4	Full range			6.5			7			10	IIIV
lio	Input offset current			25°C		1			1			1		pА
lio	input onset current			MAX			0.3			1			10	nA
lin.	Input bias current			25°C		5			5			5		рА
ΙΒ	input bias current			MAX			0.6			2			20	nA
VICR	Common-mode input voltage range			25°C	0 to 0.2			0 to 0.2			0 to 0.2			V
lau	High level output ourrent	V _{ID} = 1 V	V _{OH} = 5 V	25°C		0.1			0.1			0.1		nA
ЮН	High-level output current	VID = 1 V	V _{OH} = 15 V	Full range			1			1			1	μΑ
V/01	Low lovel output voltage	V:= - 0.5.V	lo 0.6 m/	25°C		100	200		100	200		100	200	mV
VOL	Low-level output voltage	$V_{ID} = -0.5 V,$	$I_{OL} = 0.6 \text{ mA}$	Full range			200			200			200	IIIV
loL	Low-level output current	$V_{ID} = -0.5 V$,	$V_{OL} = 300 \text{ mV}$	25°C	1	1.6		1	1.6		1	1.6		mA
Inn	Supply current	V:D = 0.5 V	No load	25°C		130	300		130	300		130	300	
lDD	(four comparators)	$V_{ID} = 0.5 V,$	INO IOau	Full range			400			400			400	μΑ

[†] All characteristics are measured with zero common-mode input voltage unless otherwise noted. Full range is 0°C to 70°C for TLC354C, -40°C to 85°C for TLC354I, and -55°C to 125°C for the TLC354M. MAX is 70°C for TLC354C, 85°C TLC354I, and 125°C for the TLC354M. IMPORTANT: See Parameter Measurement Information.

NOTE 4: The offset voltage limits given are the maximum values required to drive the output above 1.25 V or below 150 mV with a 10-kΩ resistor between the output and V_{DD}. They can be verified by applying the limit value to the input and checking for the appropriate output state.

electrical characteristics at specified free-air temperature, $V_{DD} = 5 \text{ V}$

	PARAMETER	TEST CON	IDITIONS	- +	TLC	354C		TLC	C354I		TLC	354M		UNIT
	PARAMETER	TEST CON	IDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
V/10	Input offset voltage	\/.o = \/.o = min	See Note 5	25°C		2	5		2	5		2	5	mV
VIO	input onset voltage	$V_{IC} = V_{ICR}min,$	See Note 5	Full range			6.5			7			10	1110
lio.	Input offset current			25°C		1			1			1		рА
100	input onset current			MAX			0.3			1			10	nA
lin.	Input bias current			25°C		5			5			5		рА
IB	Input bias current			MAX			0.6			2			20	nA
\/	Common-mode input			25°C	0 to V _{DD} -1			0 to V _{DD} -1			0 to V _{DD} -1			V
VICR	voltage range			Full range	0 to V _{DD} -1.5			0 to V _{DD} -1.5			0 to V _{DD} -1.5			
1	High-level output current	\/ 1 \/	V _{OH} = 5 V	25°C		0.1			0.1			0.1		nA
ЮН	High-level output current	V _{ID} = 1 V	V _{OH} = 15 V	Full range			1			1			1	μΑ
Va.	Low lovel output voltage	\/ı= - 1\/	la: - 4 m^	25°C		150	400		150	400		150	400	mV
VOL	Low-level output voltage	$V_{ID} = -1 V$	$I_{OL} = 4 \text{ mA}$	Full range			700			700			700	IIIV
l _{OL}	Low-level output current	$V_{ID} = -1 V$,	$V_{OL} = 1.5 \text{ mV}$	25°C	6	16		6	16		6	16		mA
Inn	Supply current	\/\D = 1 \/	No load	25°C		0.3	0.6		0.3	0.6		0.3	0.6	mA
IDD	OD (four comparators) $V_{ID} = 1 \text{ V},$		INO IOAU	Full range			0.8			0.8			0.8	IIIA

[†] All characteristics are measured with zero common-mode input voltage unless otherwise noted. Full range is 0°C to 70 °C for TLC354C, -40°C to 85°C for TLC354I, and -55°C to 125°C for the TLC354M. MAX is 70°C for TLC354C, 85°C TLC354I, and 125°C for the TLC354M. IMPORTANT: See Parameter Measurement Information.

switching characteristics, V_{DD} = 5 V, T_A = 25°C

PARAMETER	TEST CO	TLC35 TI	UNIT			
			MIN	TYP	MAX	
Response time	R _L connected to 5 V through 5.1 k Ω ,	100-mV input step with 5-mV overdrive		650		no
Response time	$C_L = 15 \text{ pF}^{\ddagger}$, See Note 6	TTL-level input step		200		ns

[‡]C_L includes probe and jig capacitance.

NOTE 6: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

NOTE 5: The offset voltage limits given are the maximum values required to drive the output above 4 V or below 400 mV with a 10-k Ω resistor between the output and V_{DD}. They can be verified by applying the limit value to the input and checking for the appropriate output state.

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electrical characteristics at specified free-air temperature, $V_{DD} = 1.4 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (unless otherwise noted)

	PARAMETER	TEST CON	IDITIONS	TI	LC354Y		UNIT
	PARAMETER	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
VIO	Input offset voltage	V _{IC} = V _{ICR} min,	See Note 4		2	5	mV
IIO	Input offset current				1		рА
I _{IB}	Input bias current				5		рА
VICR	Common-mode input voltage range			0 to 0.2			V
ІОН	High-level output current	V _{ID} = 1 V,	V _{OH} = 5 V		0.1		nA
VOL	Low-level output voltage	$V_{ID} = -0.5 V$,	$I_{OL} = 0.6 \text{ mA}$		100	200	mV
loL	Low-level output current	$V_{ID} = -0.5 V$,	V _{OL} = 300 mV	1	1.6		mA
I_{DD}	Supply current (four comparators)	$V_{ID} = 0.5 V$,	No load		130	300	μΑ

NOTE 4: The offset voltage limits given are the maximum values required to drive the output above 1.25 V or below 150 mV with a 10-kΩ resistor between the output and V_{DD}. They can be verified by applying the limit value to the input and checking for the appropriate output state.

electrical characteristics at specified free-air temperature, V_{DD} = 5 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS	TL	.C354Y		UNIT
	PARAMETER	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
VIO	Input offset voltage	V _{IC} = V _{ICR} min,	See Note 5		2	5	mV
IIO	Input offset current				1		pA
I _{IB}	Input bias current				5		pA
VICR	Common-mode input voltage range			0 to V _{DD} -1			V
ІОН	High-level output current	V _{ID} = 1 V,	V _{OH} = 5 V		0.1		nA
VOL	Low-level output voltage	$V_{ID} = -1 V$,	$I_{OL} = 4 \text{ mA}$		150	400	mV
lOL	Low-level output current	$V_{ID} = -1 V$,	$V_{OL} = 1.5 \text{ mV}$	6	16		mA
I_{DD}	Supply current (four comparators)	V _{ID} = 1 V,	No load		0.3	0.6	mA

NOTE 5: The offset voltage limits given are the maximum values required to drive the output above 4 V or below 400 mV with a $10-k\Omega$ resistor between the output and VDD. They can be verified by applying the limit value to the input and checking for the appropriate output state.

switching characteristics, V_{DD} = 5 V, T_A = 25°C

PARAMETER	TEST CO	ONDITIONS	Т	UNIT		
PARAWIETER	TEST CC	ONDITIONS	MIN	TYP	MAX	UNIT
Response time	R _L connected to 5 V through 5.1 k Ω ,	100-mV input step with 5-mV overdrive		650		no
Response time	$C_L = 15 \text{ pF}^{\ddagger}$, See Note 6	TTL-level input step		200		ns

[‡]CL includes probe and jig capacitance.

NOTE 6: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



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PARAMETER MEASUREMENT INFORMATION

The digital output stage of the TLC354 can be damaged if it is held in the linear region of the transfer curve. Conventional operational amplifier/comparator testing incorporates the use of a servo loop that is designed to force the device output to a level within this linear region. Since the servo-loop method of testing cannot be used, the following alternative for measuring parameters such as input offset voltage, common-mode rejection, etc., are offered.

To verify that the input offset voltage falls within the limits specified, the limit value is applied to the input as shown in Figure 1(a). With the noninverting input positive with respect to the inverting input, the output should be high. With the input polarity reversed, the output should be low.

A similar test can be made to verify the input offset voltage at the common-mode extremes. The supply voltages can be slewed as shown in Figure 1(b) for the V_{ICR} test, rather than changing the input voltages, to provide greater accuracy.

A close approximation of the input offset voltage can be obtained by using a binary search method to vary the differential input voltage while monitoring the output state. When the applied input voltage differential is equal but opposite in polarity to the input offset voltage, the output changes state.

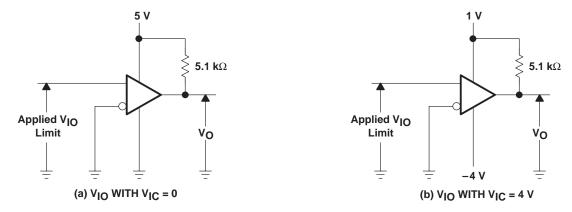


Figure 1. Method for Verifying That Input Offset Voltage is Within Specified Limits

PARAMETER MEASUREMENT INFORMATION

Figure 2 illustrates a practicle circuit for direct dc measurement of input offset voltage that does not bias the comparator into the linear region. The circuit consists of a switching-mode servo loop in which U1a generates a triangular waveform of approximately 20-mV amplitude. U1b acts as a buffer with C2 and R4 removing any residual dc offset. The signal is then applied to the inverting input of the comparator under test, while the noninverting input is driven by the output of the integrator formed by U1c through the voltage divider formed by R9 and R10. The loop reaches a stable operating point when the output of the comparator under test has a duty cycle of exactly 50%, which can only occur when the incoming triangle wave is sliced symmetrically or when the voltage at the noninverting input exactly equals the input offset voltage.

Voltage divider R9 and R10 provides a step up of the input offset voltage by a factor of 100 to make measurement easier. The values of R5, R8, R9, and R10 can significantly influence the accuracy of the reading; therefore, it is suggested that their tolerance level be 1% or lower.

Measuring the extremely low values of input current requires isolation from all other sources of leakage current and compensation for the leakage of the test socket and board. With a good picoammeter, the socket and board leakage can be measured with no device in the socket. Subsequently, this open-socket leakage value can be subtracted from the measurement obtained with a device in the socket to obtain the actual input current of the device.

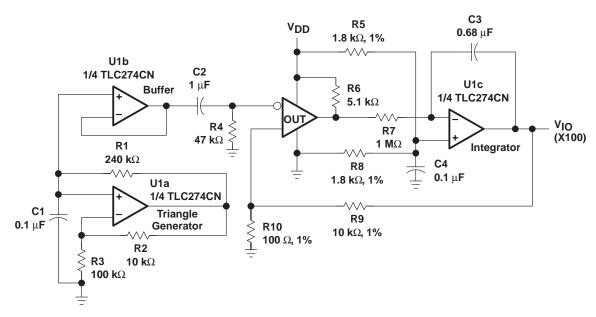
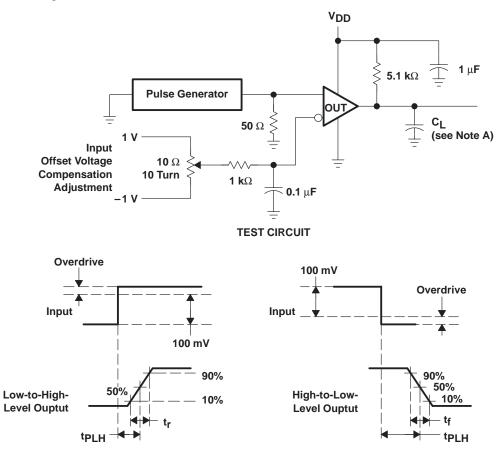


Figure 2. Test Circuit for Input Offset Voltage Measurement



PARAMETER MEASUREMENT INFORMATION

Response time is defined as the interval between the application of an input step function and the instant when the output reaches 50% of its maximum value. Response time, low-to-high-level output, is measured from the trailing edge of the input pulse. Response-time measurement at low input signal levels can be greatly affected by the input offset voltage. The offset voltage should be balanced by the adjustment at the inverting input (as shown in Figure 3) so that the circuit is just at the transition point. Then a low signal, for example, 105-mV or 5-mV overdrive, causes the output to change.



VOLTAGE WAVEFORMS

NOTE A: CL includes probe and jig capacitance.

Figure 3. Response, Rise, and Fall Times Test Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TLC354CD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC354C	Samples
TLC354CN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TLC354CN	Samples
TLC354CPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	P354	Samples
TLC354CPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	P354	Samples
TLC354ID	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC354I	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC354CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

	Device Package Type		Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ſ	TLC354CPWR	TSSOP	PW	14	2000	356.0	356.0	35.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TLC354CD	D	SOIC	14	50	505.46	6.76	3810	4
TLC354CN	N	PDIP	14	25	506	13.97	11230	4.32
TLC354CPW	PW	TSSOP	14	90	530	10.2	3600	3.5
TLC354ID	D	SOIC	14	50	505.46	6.76	3810	4



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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